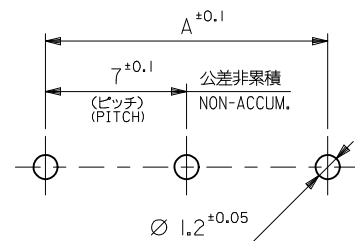
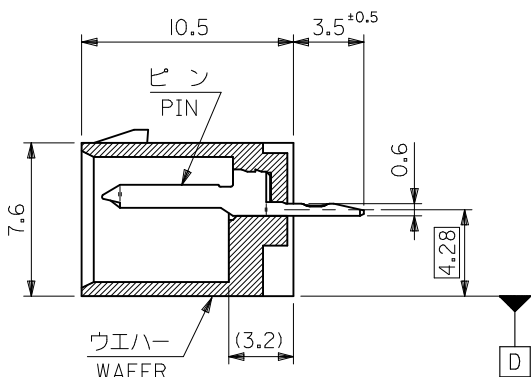


- 注記 NOTES**
1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
 2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り)、UL94V-0
WAFER : PBTP (G.F 15%), UL94V-0
ピン : 黄銅、ニッケル下地 錫メッキ (t=0.254)
PIN : BRASS, TIN OVER NICKEL PLATING (t=0.254)
 3. 本製品は 53265-**20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53265-**20.



基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	54.6	53.2	49.0	53265-0829	8
	47.6	46.2	42.0	-0729	7
	40.6	39.2	35.0	-0629	6
	33.6	32.2	28.0	-0529	5
	26.6	25.2	21.0	-0429	4
8.7	19.6	18.2	14.0	-0329	3
6.1	12.6	11.2	7.0	53265-0229	2
(D)	C	B	A	TRAY PACKAGE	CKT.
				ORDER No. オート番号	極数

REVISED EC NO: J2009-1054 DRWN: MABEI 2009/02/17 CHKD: HYAJIMA 2009/02/18 APPR: NUKITA 2009/02/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 53265-**29
	10 UNDER	±0.2	DRAWN BY Y. WADA	DATE '04/04/22	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.) -LEAD FREE-	DESIGN UNITS METRIC
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/22	APPROVED BY M. SASAO	THIRD ANGLE PROJECTION
	30 OVER	±0.3	DATE '04/04/22	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MOLEX INCORPORATED SD-53265-005
A	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					1 OF 1